PRODUCT CHANGE NOTICE

Alternate Bond Wire Material for Assembly of Intersil ISL6251* QSOP Packaged Products

Refer to:
PCN11037

Date: April 14, 2011

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To: Our Valued Intersil Customer

Subject: **Alternate Bond Wire Material for Assembly of Intersil ISL6251* QSOP Packaged Products –** *Carsem (CAM) Ipoh, Malaysia*

This notice is to inform you that Intersil has qualified copper bond wire as an alternate to the gold bond wire currently used for assembly of the ISL6251* QSOP (Quarter Size Outline Plastic) packaged products at the Carsem (CAM) facility, located in Ipoh, Malaysia. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep and equivalent reliability performance. The product and package specific qualification activities are complete.

Products affected: **ISL6251AHAZ** **ISL6251AHAZ-T** **ISL6251HAZ** **ISL6251HAZ-T**

The Carsem (CAM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and currently qualified as a supplier to Intersil for assembly of QSOP packaged products. There will be no change in the mold compound, die attach, or package outline drawing (POD). Products assembled with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260°C per J-STD-020). The qualified material set combinations for assembly and other key items are as follows:

Key Items	Current	New (Alternate)
Mold Compound	Sumitomo EME-G600C	Sumitomo EME-G600C
Die Attach	Ablebond 8290	Ablebond 8290
Bond Wire	1.3 mil Gold (Au)	1.3 mil Copper (Cu)
Moisture Sensitivity Level	2	3
Device Marking - Site Code	G	X

The qualification plan for copper bond wire assembly was designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Products affected by this change that are assembled using either gold or copper bond wire material are identifiable via Intersil's internal traceability system and by the assembly site code (country of assembly) marked on the devices. The site code for product assembled with copper bond wire is "X". The site code for product assembled at CAM with gold bond wire is "G".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled using either gold or copper bond wire beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

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PCN11037 – ISL6251 Qualification Summary

Test Name	Precondition	Lots	Sample Size	Condition	Duration	Rejects
HAST UNBIAS	L3 PBFREE	4	459	130C, 85%RH	96	0
TEMP CYCLE	L3 PBFREE	4	459	-65C TO 150C	500	0
MRT LEVEL 3	L3 PBFREE	1	44	30C, 60%RH	192	0
HTS		3	75	150C	1000	0